

Electronic Supplementary Information for

Versatile method for bonding hard and soft materials

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This supporting information includes:

Figure S1: Images of (a) HDPE-PDMS (b) Fe-PDMS devices bonded to aluminum jig. Parts released after tensile strength measurement. The hard materials correspond to HDPE (c) and Fe (d).

Figure S2: Pictures showing contact angle of pristine and plasma-treated substrates

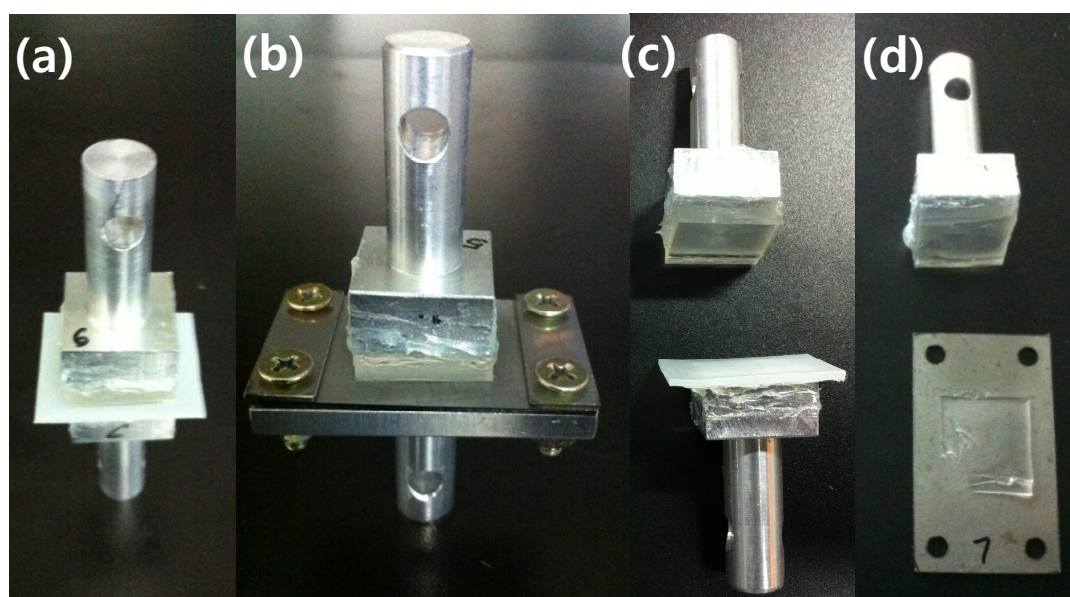


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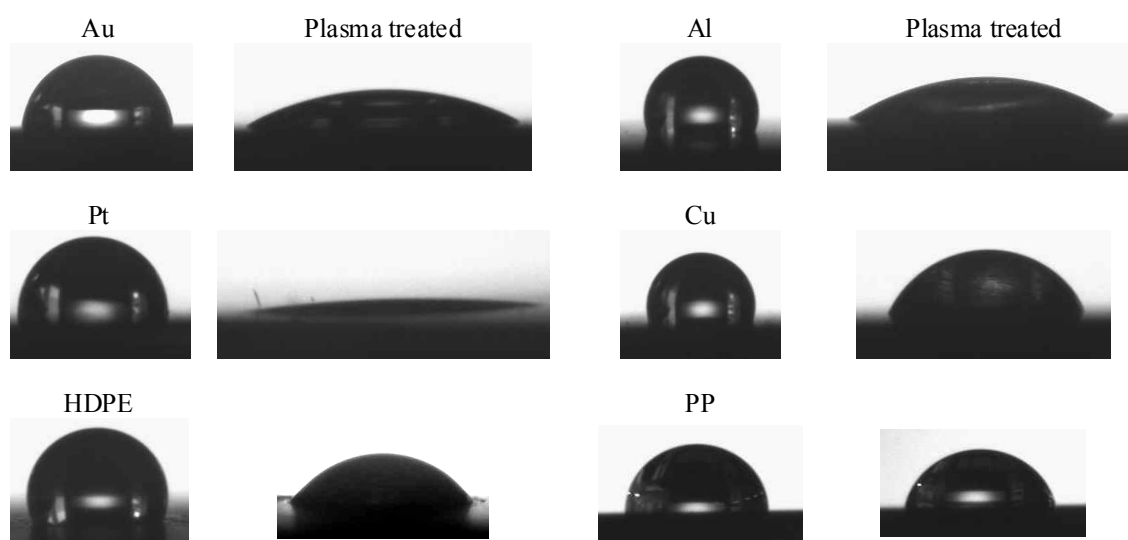


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